

J.S.T. Mfg. Co., Ltd.

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T	Request for Change	Issue No.	Rev.
Title of Document:		G21-07011	1
Cuatamari		Issue date:	
Customer:		October 19, 2021	
Title subject:	XM connector Housing: Addition of resin material	Revision date:	
		October 29, 202	1

Please take note that we would like to add a material manufacturer of the PA 66 resin used for the XM connector Housing due to the supply restrictions by current manufacturer as follows.

1. Target product and Part Number

XM connector

Part number: XMP-*V*-*, XMR-*V(*)



2. Timing of implementation

The supply of materials will be restricted from November 2021 onwards. Therefore, it will be conducted as soon as preparations have been made.

3. Contents of the change

The housing resin material of the aforementioned subject products shall be added.

UL/CSA certification for additional products (made of additional resin) is currently in the process of applying. Until UL/CSA certification for additional products is completed, "(SU)" as identification symbol shall be suffixed to the current part numbers in order to distinguish the additional products.

After obtaining UL/CSA certification for additional products, we will remove the identification symbol "(SU)" and unify to the original part number.

-	Resin material maker	Resin Part No.	Part No.
Current product	DSM	3010N5	XMP-*V*-* XMR-*V(*)
Additional product (Advance release product) <applying csa="" for="" ul=""></applying>	LANXESS	A30SFN31	XMP-*V*-* (SU) XMR-*V(*) (SU)
Additional product (After UL/CSA certification)	DSM LANXESS	3010N5 A30SFN31	XMP-*V*-* XMR-*V(*)

^{*} For the time being, additional products will only be available in natural color. We will report on the various colored products as soon as they are ready.

4. Reason for the change

Due to difficulty of procuring the PA 66 resin material due to the supply restrictions by current resin manufacturer.

Your thought understanding and consideration would be very much appreciated.

-End-

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